# Electronic Acknowledgement Receipt FES ID: 1046031 Application Number: 10650193 Confirmation Number: 6245 Semiconductor device having silicon-diffused metal wiring layer and its Title of Invention: manufacturing method First Named Inventor: Koichi Ohto Customer Number: 23373 Filer: Howard Leonard Bernstein/Melissa Patrick Filer Authorized By: Howard Leonard Bernstein Attorney Docket Number: Q77191 Receipt Date: 12-MAY-2006 Filing Date: 28-AUG-2003 Time Stamp: 14:46:15 Application Type: Utility International Application Number:

### Payment information:

Submitted with Payment no

## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		Q77191Response.pdf	92765	yes	5

	Multipart Description		
	Doc Desc	Start	End
	Amendment - After Non-Final Rejection	1	1
	Applicant Arguments/Remarks Made in an Amendment	2	5
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#### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

#### National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/IDO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filling Receipt, in due course.